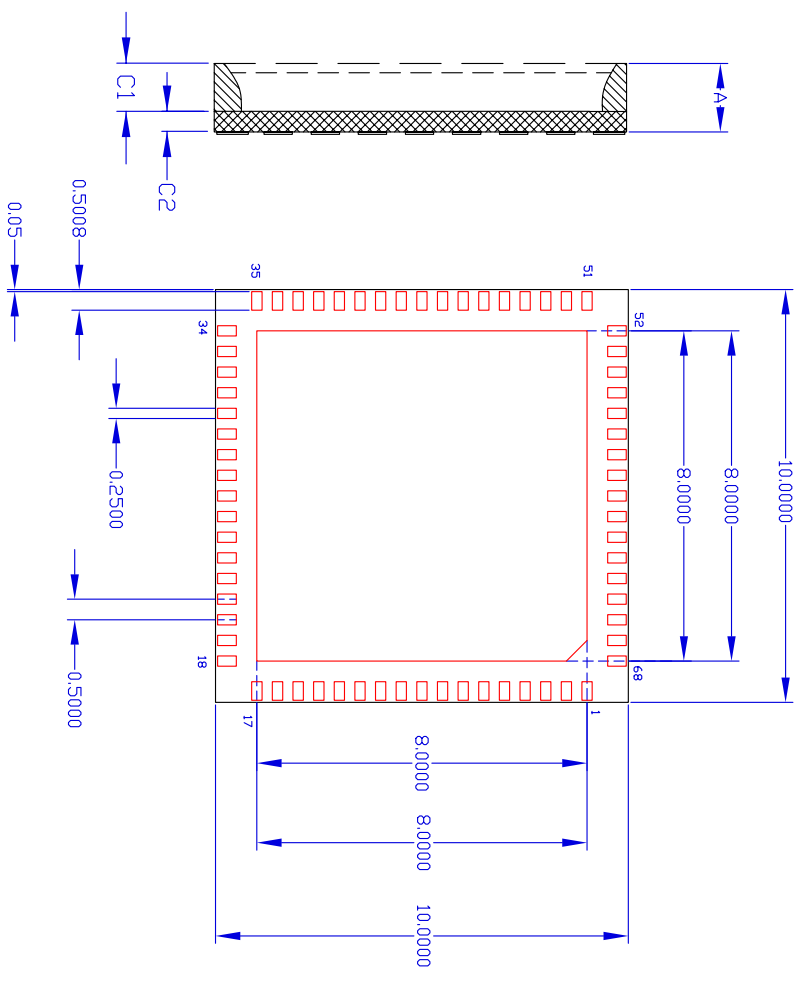
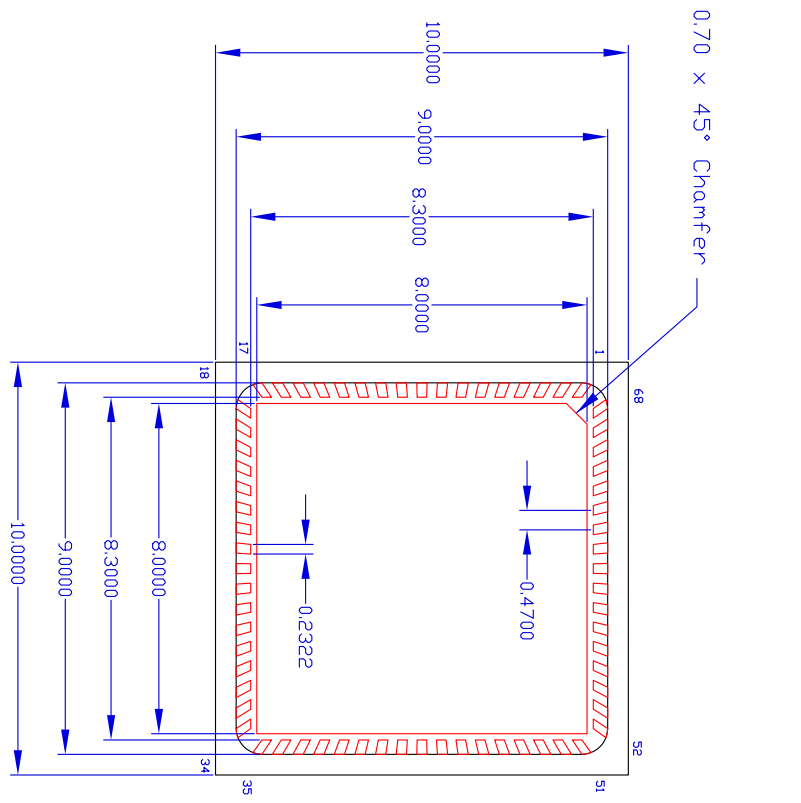


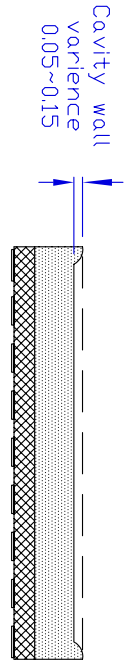
TOP VIEW

SIDE VIEW

BOTTOM VIEW



SIDE VIEW



HEIGHT TABLE			
SERIES	C1	C2	A
A-QFN	0.63	0.27	0.90
A-TQFN	0.38	0.27	0.65
TOL	+/- 0.10	+/- 0.05	+/- 0.15

OTHER SIZES AVAILABLE

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Note:

- Organic substrate
- Cavity Dam: Hysol FP4451TD
- Pads: Cu/Ni/Au
- Copper Thickness: 12µm~18µm (0.5~0.7mil)
- Bonding Pad Gold Thickness: 1.3µm (50 micro-inch)
- PCB Pads Gold Thickness: 0.13µm (5 micro-inch)
- Nickel Thickness: 38µm (150 micro-inch)
- All Dimensions Are mm

TOLERANCES UNLESS NOTED:		APPROVALS		DATE	
X.XX ±	INCHES	DRWN	TA	11/29/08	
X.XXX ±	MILLIMETERS	ENG			
X.XXXX ±		MFG			
ANGLES ±		TITLE			
THIRD ANGLE PROJECTION:		68-LEAD 10MM P=0.50MM			
SCALE	SIZE	DRAWING NO.			
NONE	A	456810			
REV		A			
DO NOT SCALE DRAWING		SHEET 1 OF 1			

